ABSTRACT

AUTOMATIC WIRE TAIL ADJUSTMENT SYSTEM FOR WIRE BONDERS

A capillary is utilized to form the wedge wire bond comprised in a wire interconnection. A wire holding device is located above a wire clamp and the capillary to secure the wire while the wire clamp is open and not clamping onto the wire. The wire clamp and the capillary may be lifted relative to the wire in a direction away from the wedge wire bond and towards the wire holding device so as to pay out a length of wire from the capillary. At a predetermined height of the capillary, the wire clamp is closed to clamp onto the wire, and thereafter, the capillary and wire clamp may be moved further away from the wedge wire bond to cause the wire to break away from the wedge wire bond and to form the wire tail with a desired length extending from the capillary.

(FIG. 3)